

IN THE CLAIMS:

Please amend the claims as shown below. The status of the claims after amendment will be as follows.

Claims 1 - 7 (canceled)

8. (currently amended) A lead-free solder paste comprising a first solder alloy powder of a first solder alloy, a second solder alloy powder of a second solder alloy, and a flux mixed with the first and second solder alloy powders, wherein the first solder alloy and the second solder alloy have a difference of at least 10°C in their main peak temperatures measured by differential thermal analysis, ~~and~~ the overall composition after melting of the first and second solder alloy powders is 3 - 4 mass % of Ag, 3 - 10 mass % of In, 0 - 1 mass % of Bi, 0 - 1 mass % Cu, and a balance of Sn, and the first solder alloy contains 6 - 20 mass % of In.

9. (previously presented) A solder paste as claimed in claim 8 wherein the first solder alloy is a Sn-Ag-In alloy and the second solder alloy is a Sn-Ag alloy.

10. (previously presented) A solder paste as claimed in claim 9 wherein:

the first solder alloy contains 3 - 4 mass % of Ag and 6 - 20 mass % of In; and